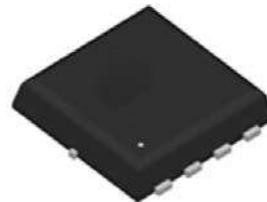


20V P-Ch Power MOSFET

DFN3x3

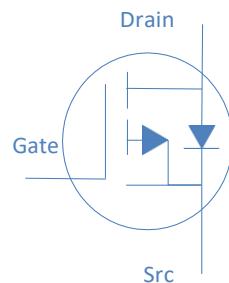
Features:

- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% R_g Tested
- ◇ Lead Free, Halogen Free

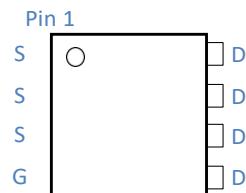


Application :

- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial



| | | |
|---|-----|----|
| V _{DS} | -20 | V |
| R _{DS(on),typ} V _{GS} =4.5V | 5.6 | mΩ |
| I _D (Silicon Limited) | -46 | A |



| Part Number | Package | Marking |
|-------------|---------|----------|
| KWTM063P02 | DFN3*3 | TM063P02 |

Absolute Maximum Ratings at T_j=25°C (unless otherwise specified)

| Parameter | Symbol | Conditions | Value | Unit |
|--|-----------------------------------|-------------------------------|------------|------|
| Continuous Drain Current (Silicon Limited) | I _D | T _C =25°C | -46 | A |
| | | T _C =100°C | -29 | |
| Drain to Source Voltage | V _{DS} | - | -20 | V |
| Gate to Source Voltage | V _{GS} | - | ±12 | V |
| Pulsed Drain Current | I _{DM} | - | -180 | A |
| Avalanche Energy, Single Pulse | E _{AS} | L=0.1mH, T _C =25°C | 115 | mJ |
| Power Dissipation | P _D | T _C =25°C | 21 | W |
| Operating and Storage Temperature | T _J , T _{stg} | - | -55 to 150 | °C |

Absolute Maximum Ratings

| Parameter | Symbol | Max | Unit |
|--|------------------|-----|------|
| Thermal Resistance Junction-Ambient | R _{θJA} | 50 | °C/W |
| Thermal Resistance Junction-Ambient (steady state) | R _{θJC} | 6 | °C/W |

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Static Characteristics

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------------------------------|-----------------------------|---|-------|------|-----------|------------------|
| | | | min | typ | max | |
| Drain to Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}}=0\text{V}, I_D=-250\mu\text{A}$ | -20 | - | - | V |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}}=V_{\text{DS}}, I_D=-250\mu\text{A}$ | -0.4 | -0.6 | -1.2 | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-16\text{V}, T_j=25^\circ\text{C}$ | - | - | -1 | μA |
| | | $V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-12\text{V}, T_j=125^\circ\text{C}$ | - | - | -10 | |
| Gate to Source Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |
| Drain to Source on Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}}=-4.5\text{V}, I_D=-20\text{A}$ | - | 5.6 | 6.3 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=-2.5\text{V}, I_D=-20\text{A}$ | - | 6.7 | 7.5 | |
| | | $V_{\text{GS}}=-1.8\text{V}, I_D=-20\text{A}$ | - | 8.4 | 9.5 | |
| | | $V_{\text{GS}}=-1.5\text{V}, I_D=-20\text{A}$ | - | 11.5 | 15 | |
| Transconductance | g_{fs} | $V_{\text{DS}}=-5\text{V}, I_D=-20\text{A}$ | - | 52 | - | S |
| Gate Resistance | R_G | $V_{\text{GS}}=15\text{mV}, V_{\text{DS}}=0\text{V}, f=1\text{MHz}$ | - | 3.3 | - | Ω |

Dynamic Characteristics

| | | | | | | |
|-------------------------------|----------------------------|---|---|------|---|----|
| Input Capacitance | C_{iss} | $V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-10\text{V}, f=1\text{MHz}$ | - | 6945 | - | pF |
| Output Capacitance | C_{oss} | | - | 605 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 515 | - | |
| Total Gate Charge | Q_g | $V_{\text{DD}}=-10\text{V}, I_D=-20\text{A}, V_{\text{GS}}=-4.5\text{V}$ | - | 49 | - | nC |
| Gate to Source Charge | Q_{gs} | | - | 10 | - | |
| Gate to Drain (Miller) Charge | Q_{gd} | | - | 7.6 | - | |
| Turn on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=-10\text{V}, I_D=-1\text{A}, V_{\text{GS}}=-4.5\text{V}, R_G=6\Omega,$ | - | 20 | - | ns |
| Rise time | t_r | | - | 50 | - | |
| Turn off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 250 | - | |
| Fall Time | t_f | | - | 120 | - | |

Reverse Diode Characteristics

| | | | | | | |
|-------------------------|-----------------|--|---|-----|------|----|
| Diode Forward Voltage | V_{SD} | $V_{\text{GS}}=0\text{V}, I_F=-20\text{A}$ | - | | -1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_F=-20\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$ | - | 75 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 480 | - | nC |

Fig 1. Typical Output Characteristics

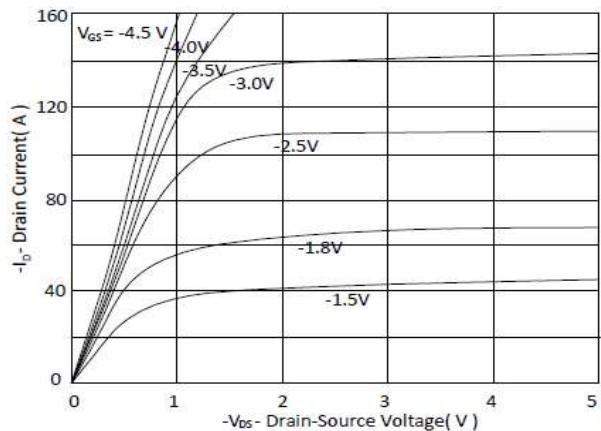


Figure 2. On-Resistance vs. Gate-Source Voltage

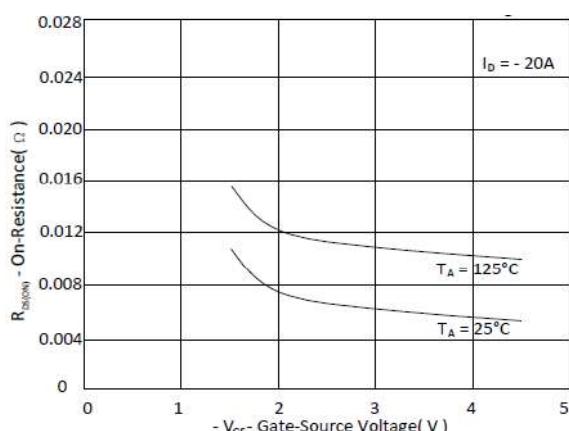


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

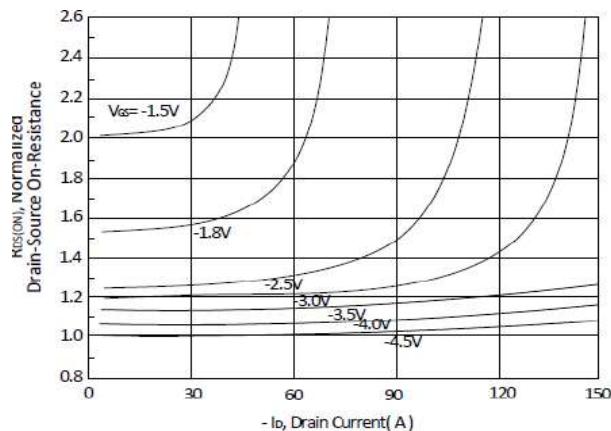


Figure 4. Normalized On-Resistance vs. Junction Temperature

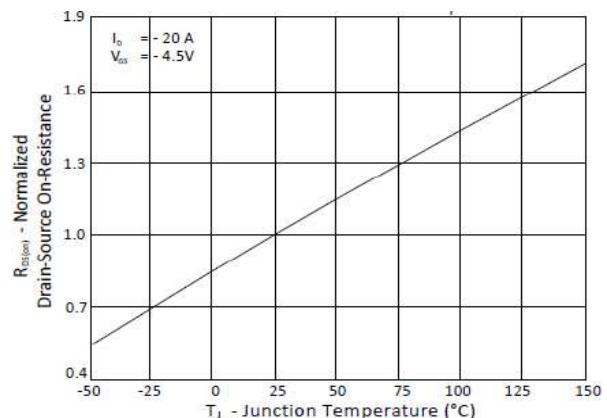


Figure 5. Typical Transfer Characteristics

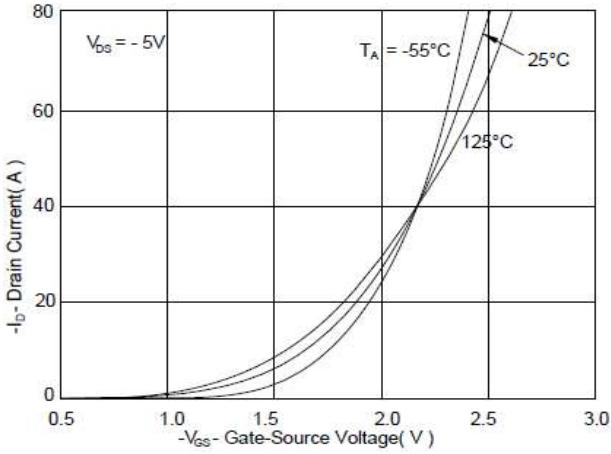


Figure 6. Typical Source-Drain Diode Forward Voltage

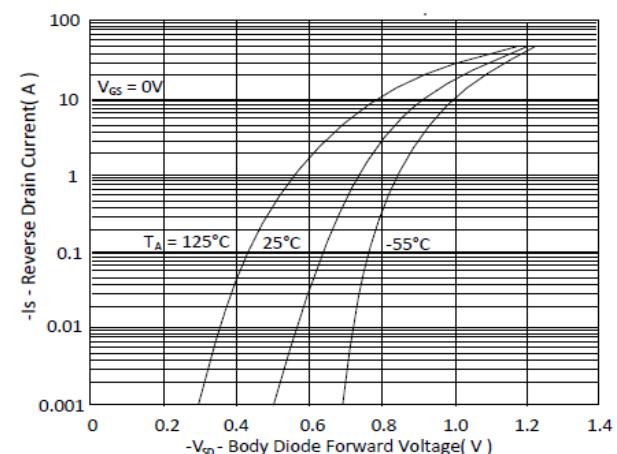


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

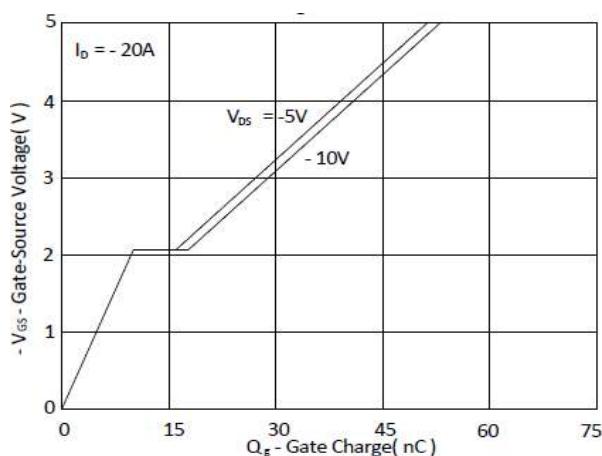


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

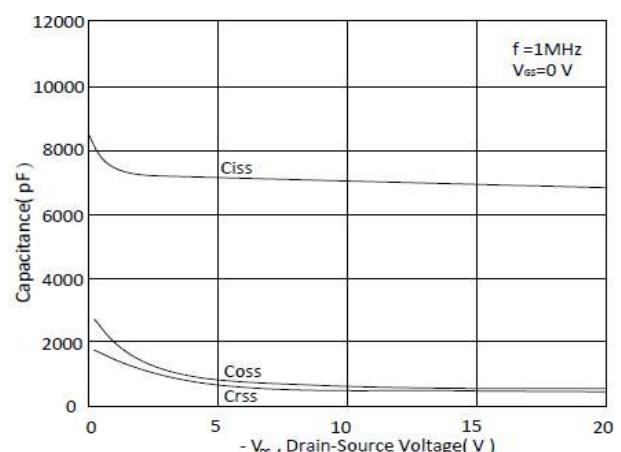


Figure 9. Maximum Safe Operating Area

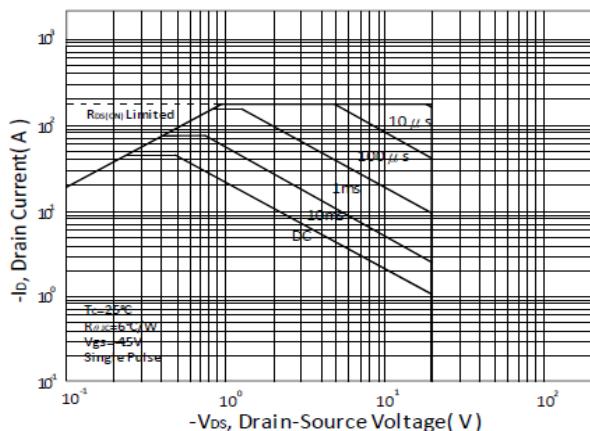


Figure 10. Single Pulse Maximum Power Dissipation

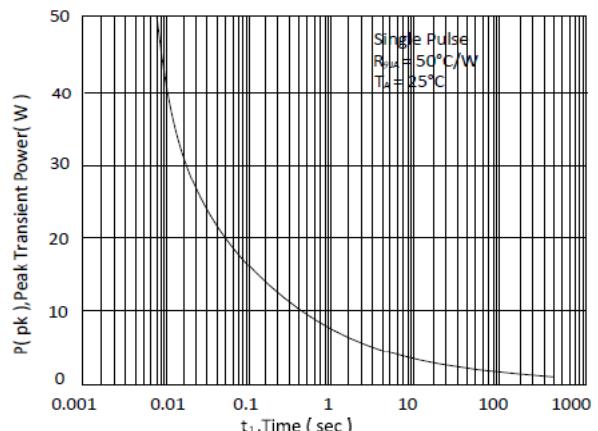
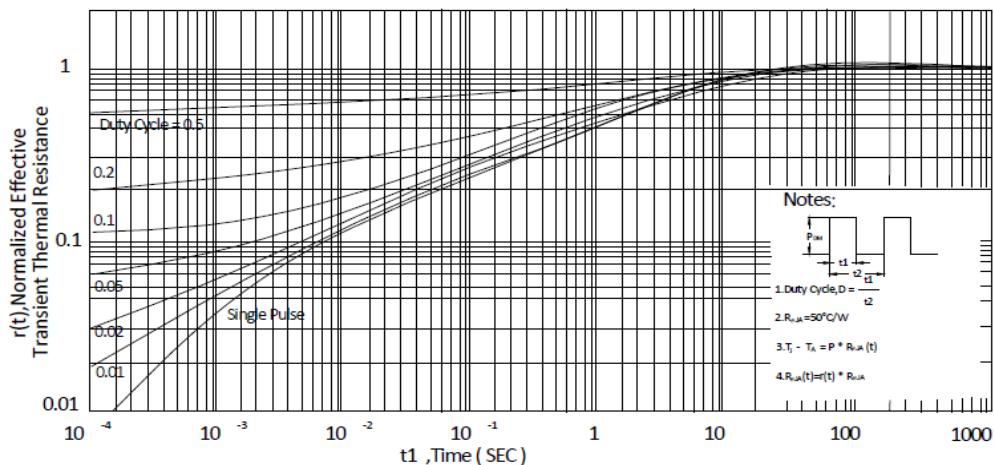
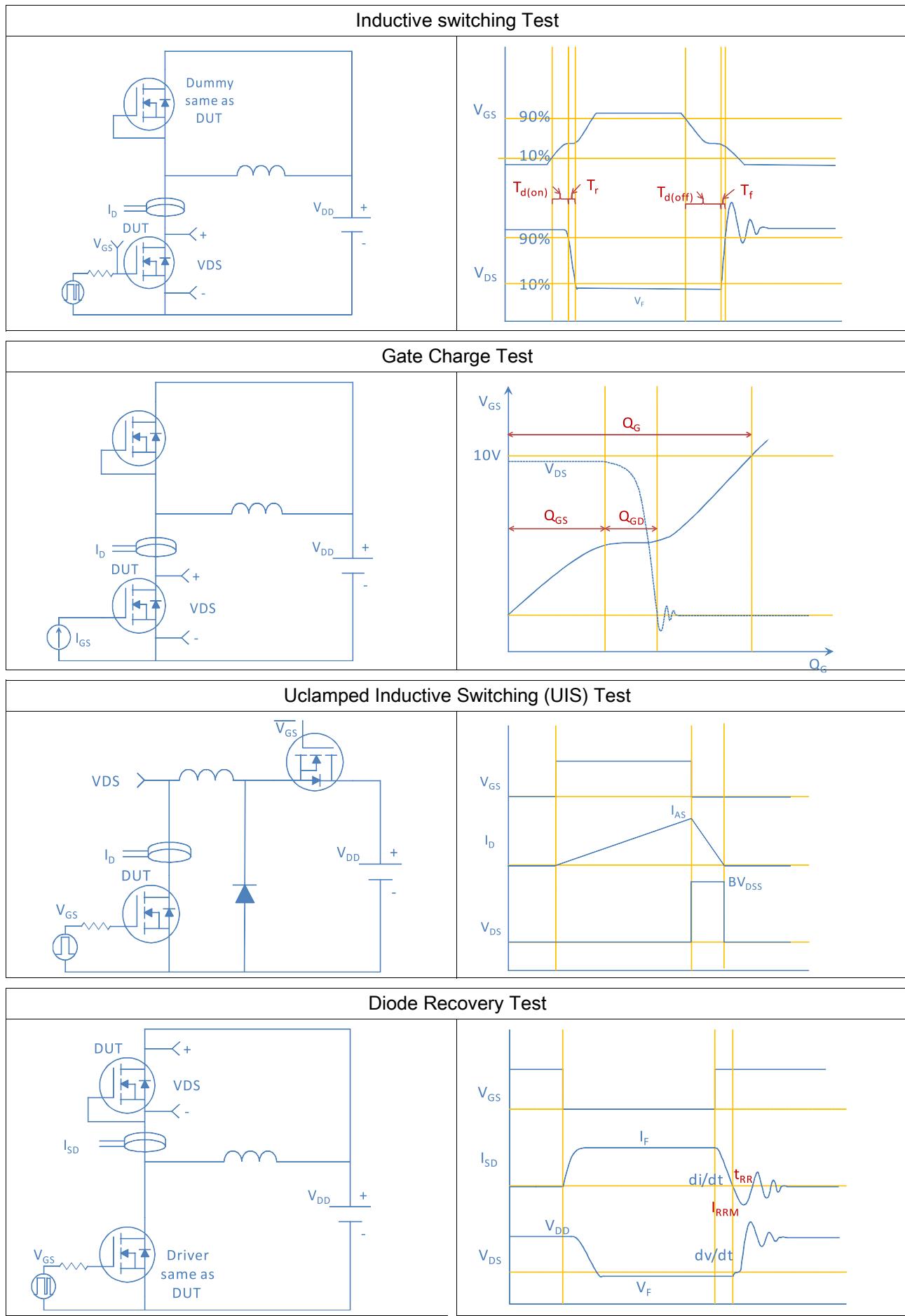


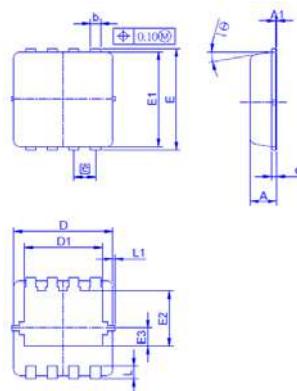
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient





Package Outline

DFN3*3_P, 8leads



Dimension in mm

| Dimension | A | A1 | b | c | D | D1 | E | E1 | E2 | E3 | e | L | L1 | θ1 |
|-----------|------|------|------|-------|------|------|------|------|------|-------|------|------|------|-----|
| Min. | 0.70 | 0 | 0.24 | 0.10 | 2.95 | 2.25 | 3.15 | 2.95 | 1.65 | | | 0.30 | | 0° |
| Typ. | 0.80 | | 0.30 | 0.152 | 3.00 | 2.35 | 3.20 | 3.00 | 1.75 | 0.575 | 0.65 | 0.40 | 0.13 | 10° |
| Max. | 0.90 | 0.05 | 0.37 | 0.25 | 3.15 | 2.45 | 3.40 | 3.15 | 1.96 | | | 0.50 | | 12° |